

INTERNEPCON / UK '83



It's the sixteenth time around and the Internepcon exhibition and conference bandwagon keeps rolling on.

Next week the electronics industry will converge on Brighton's Metropole Convention Centre where over 400 suppliers will be showing products ranging from printed circuit board production equipment to soldering tools and fibre optic cables to modular power supplies. Any visitor who can provide documentary evidence of a visit to every stand will

win the *Electronics Weekly* Gold Corn Plaster Award, but the dedicated exhibition visitor will be hard-pressed to find a greater array of electronics products in any exhibition in the UK. On the next nine pages we preview the conference and exhibition.

All tastes catered for

ALONGSIDE the Internepcon exhibition organisers Cahners will be running its usual comprehensive conference programme. It is designed to cater to all tastes and complements

the exhibits on parade in the Metropole.

Three main headings have been chosen to attract conference delegates.

They are printed circuits;

equipment practice; and hybrid microelectronics.

On the opening day David Small from British Telecom's Martlesham Heath Research Centre will be chairing a session titled: Substrates for Surface Mounted Devices - Methods and Practices.

City brokers may be out in force for the first paper in this session, the PCB Industry 1983-1990 which is being given by Dr Maurice Sage of the noted market consultants BPA Technology and Management Ltd.

Other contributors to the session are Welwyn Electric's T. Hogan who will speak on Chip Carrier Mounting and Mike Anstey of ICDC who featured in the pages of *Electronics Weekly* in August. He will be talking about Interconnecting Leadless Chip Carriers.

On Tuesday afternoon, somebody who I hope will not be too offended by the title the Grand Old Man of the UK pcb industry, Henry Manfield, will kick off a new innovation - the PCB boardwalk.

Manfield will be explaining the technical background to an exhibition centrepiece which weeks to provide an insight into the automated production of bare board printed circuits. The Manfield explanations will be presented in two parts, the second paper to be presented on Wednesday afternoon.

The testing of PCBs should provoke a lively discussion on the Wednesday morning. Genrad's Brendan Davis will be chairing the session which includes contributions from his colleague Chris Sheldon, Zehnelt and Hewlett-Packard.

The Equipment Practice Sessions will feature papers on the Interconnection and Packaging Aspects of IBM's Large Processors, which looks by the title as if it could be a conference in its own right.

Connectors and Systems for Hostile Environments, chaired



Sage: Charting the PCB industry.



Anstey: Talking about interconnections.

BS9000 in their closets can come out into the open and put their views.

There will also be a panel discussion CECC, IEC and BS9000 specifications as applied specifically to the hybrid microelectronics sector.

VLSI packaging and new applications of hybrid microelectronics are two other interesting sessions.

In addition there will be two

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